

North America Flip Chip Market By Packaging Technology (2.5D IC, 3D IC, and 2D IC), By Bumping Technology (Copper Pillar, Gold Bumping, Solder Bumping and Others), By End User (Electronics, Industrial, IT & Telecom, Automotive, Healthcare & Life Sciences, Aerospace & Defense and Others), By Country, Industry Analysis and Forecast, 2020 - 2026

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Abstracts

The North America Flip Chip Market would witness market growth of 7.5% CAGR during the forecast period (2020-2026).

Flip Chip technology is the method used to connect semiconductor devices such as Integrated Circuit Chips and Microelectromechanical Systems (MEMS) to external circuits with solder bumps that have been placed on chip pads. The device is then placed on the external circuitry with its top side down and correctly positioned such that its pads correspond with the corresponding pads on the outer circuit. Flip Chip provides reduced device size (as packaging density increases) and improved efficiency. It's better than wire bonding, as all bonds form simultaneously.

One major advantage that flip chip provides over other technology is its ability to provide higher-frequency data transfer between devices. This is attributable to the fact that the contacts are made by flip-chip bumps, which the duration and, in effect, offer improved electrical efficiency. The surge in demand for high-energy microwave, ultrasonic frequency operations and growing demand for high-speed handheld devices is projected to lead to the growth of the global flip-chip industry in the near future.

Nevertheless, the use of additional wafer bumps and a higher price substrate restricts

market growth. Furthermore, the number of input output ports provided on these chips cannot be customized after production due to their extremely complex architecture and compact size. Collectively, these factors also hinder the growth of the overall market. On the contrary, technological advancements by research and development facilities and expenditure by leading players in the industry are expected to reduce the effect of the restraint factor, thereby offering remunerative opportunities for the expansion of the overall flip-chip sector.

Based on Packaging Technology, the market is segmented into 2.5D IC, 3D IC and 2D IC. Based on Bumping Technology, the market is segmented into Copper Pillar, Gold Bumping, Solder Bumping and Others. Based on End User, the market is segmented into Electronics, Industrial, IT & Telecom, Automotive, Healthcare & Life Sciences, Aerospace & Defense and Others. Based on countries, the market is segmented into U.S., Mexico, Canada, and Rest of North America.

The market research report covers the analysis of key stake holders of the market. Key companies profiled in the report include 3M Company, Advanced Micro Devices, Inc., Amkor Technology, Inc., Apple, Inc., Fujitsu Limited, Intel Corporation, IBM Corporation, Samsung Electronics Co., Ltd., Texas Instruments, Inc., and Taiwan Semiconductor Manufacturing Company.

Scope of the Study

Market Segmentation:

By Packaging Technology

2.5D IC

3D IC

2D IC

By Bumping Technology

Copper Pillar

Gold Bumping

Solder Bumping

Others

By End User

Electronics

Industrial

IT & Telecom

Automotive

Healthcare & Life Sciences

Aerospace & Defense

Others

By Country

US

Canada

Mexico

Rest of North America

Companies Profiled

3M Company

Advanced Micro Devices, Inc.

Amkor Technology, Inc.

Apple, Inc.

Fujitsu Limited

Intel Corporation

IBM Corporation

Samsung Electronics Co., Ltd.

Texas Instruments, Inc.

Taiwan Semiconductor Manufacturing Company

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